**Equipment overview**

This equipment is de-bonding equipment for separating carrier glass without stress by irradiating LASER.

**Feature**

**Reducing damage to the device**
The wavelength of the LASER is 355nm. LASER energy is absorbed in extreme thin layer of resin. Hence, it is possible to prevent device damage caused by LASER.

**Applicable to large size panel**
Panel size: Up to 600mm x 600mm

**High speed de-bonding**
By adopting high speed LASER system, high speed irradiation can be achieved compared to conventional scanner system.

**Applicable to warpage**
By adopting stable LASER beam against fluctuating in warpage, substrate with some warpage also can be de-bonded with stability. (“Stable LASER” means the evenness in beam figure, size, energy density)

**Soot prevention after LASER irradiation**
By introducing a dust remover, the soot is not scattered in the equipment, reducing its intrusion into the sliding part of the equipment.

※ Licensed by IBM for laser de-bonding technology ※

These specifications are subject to change for product improvement without prior notice.
Basic configuration

- LASER generator
- Scanner
- Substrate stage
- Chiller
- Dust collector

Wave length

355nm (UV LASER)

Scan speed

>20m/s

Substrate applicable size

For panel size: Up to 600 × 600mm
For wafer size: Up to φ300mm

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